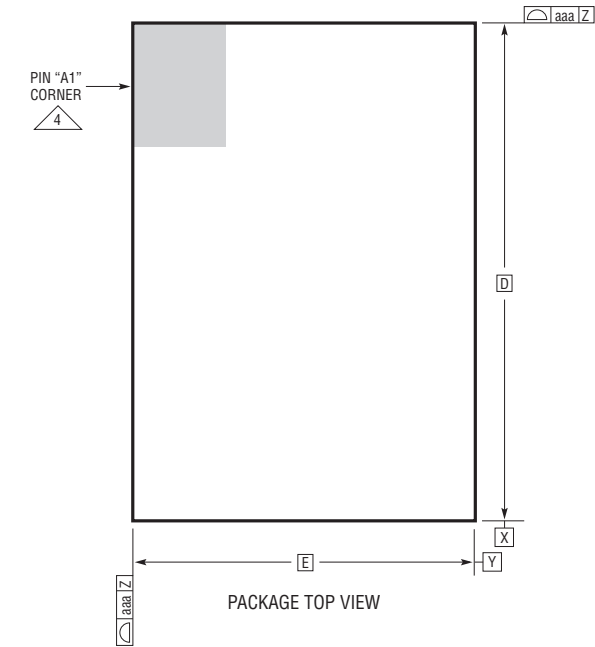
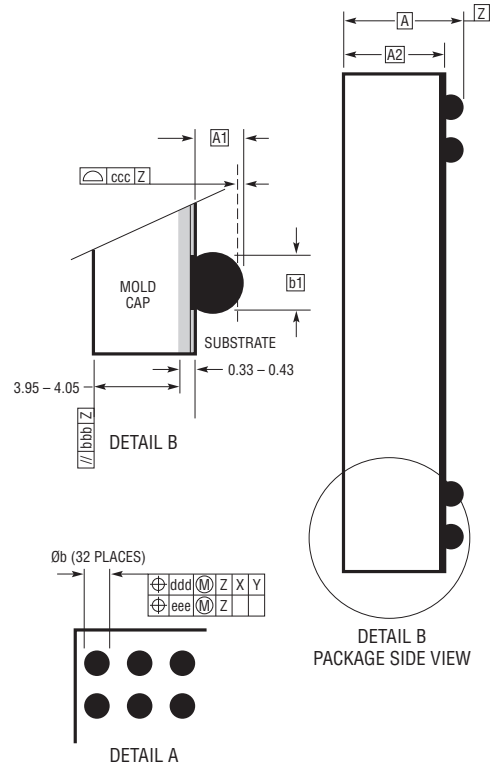


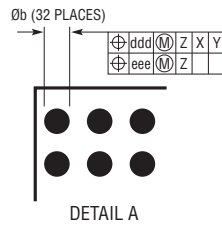
BGA Package
32-Lead (15mm × 11.25mm × 4.98mm)
 (Reference LTC DWG # 05-08-1860 Rev B)



PACKAGE TOP VIEW

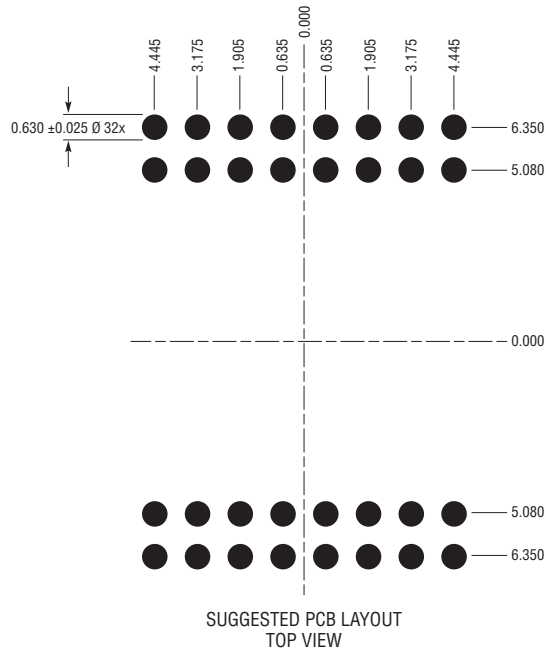


DETAIL B
PACKAGE SIDE VIEW

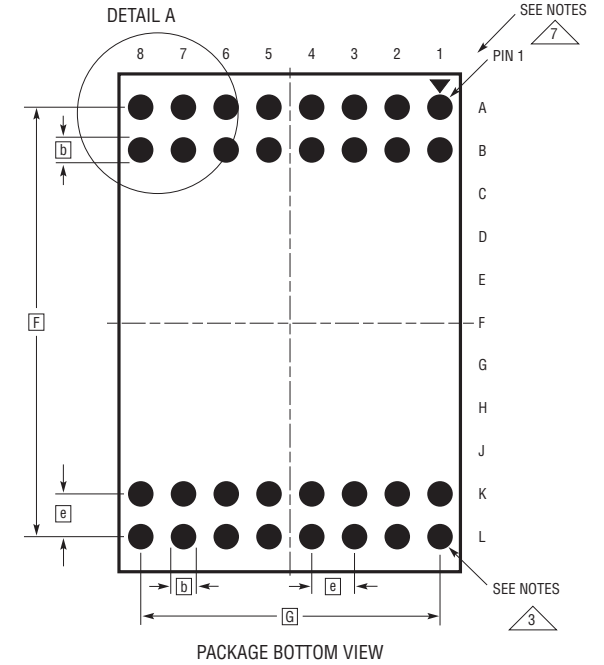


DETAIL A

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	4.78	4.98	5.18	
A1	0.50	0.60	0.70	
A2	4.28	4.38	4.48	
b	0.73	0.78	0.83	
b1	0.60	0.63	0.66	
D		15.0		
E		11.25		
e		1.27		
F		12.70		
G		8.89		
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	
TOTAL NUMBER OF BALLS: 32				



SUGGESTED PCB LAYOUT
TOP VIEW



PACKAGE BOTTOM VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

2. ALL DIMENSIONS ARE IN MILLIMETERS

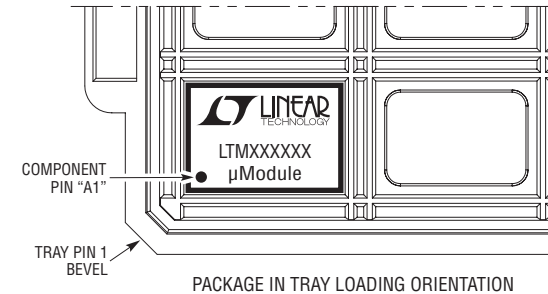
3 BALL DESIGNATION PER JESD MS-028 AND JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu

7  PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION